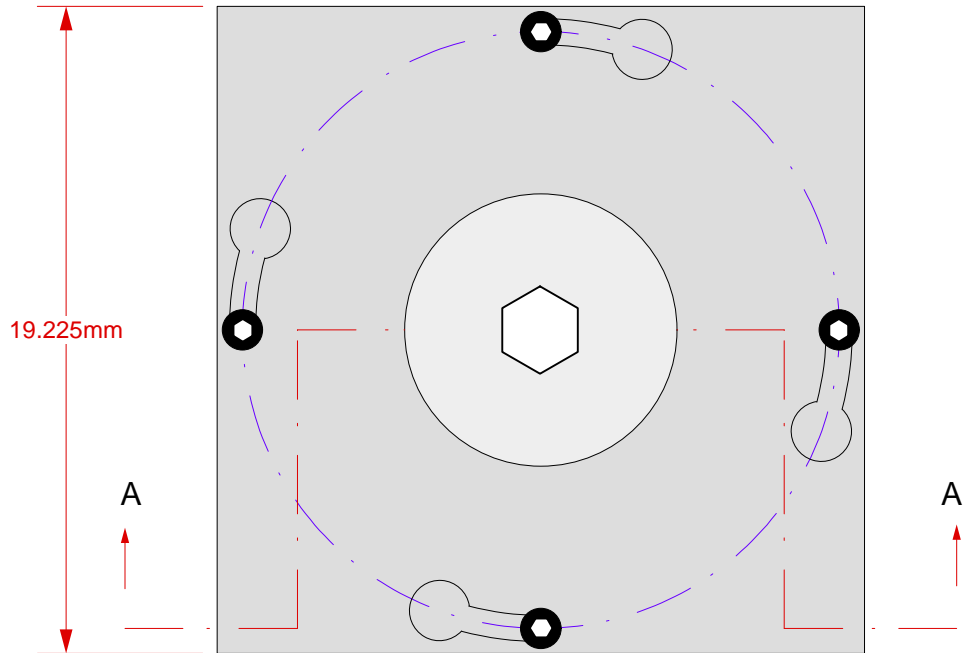


Top View

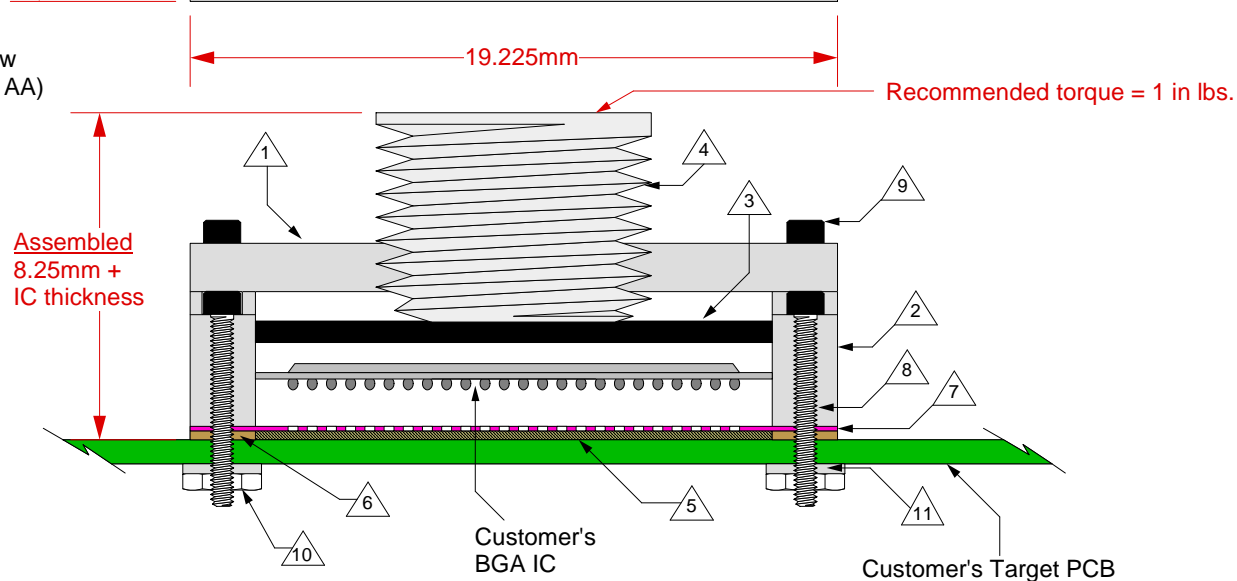


# GHz BGA Socket - Direct mount, solderless

## Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Ball guide prevents over compression of elastomer
- Easily removable swivel socket lid

Side View  
(Section AA)



- 1 Socket Lid: Black anodized Aluminum. Thickness = 2.5mm.
- 2 Socket base: Black anodized Aluminum. Thickness = 5mm.
- 3 Compression Plate: Black anodized Aluminum. Thickness = 2.5mm.
- 4 Compression screw: Clear anodized Aluminum. Thickness = 5mm, Hex socket = 5mm.
- 5 Elastomer: 40 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.75mm.
- 6 Elastomer Guide: Non-clad FR4. Thickness = 0.725mm.
- 7 Ball Guide: Kapton polyimide.
- 8 Socket base screw: Socket head cap, Alloy steel with black oxide finish, 0-80 fine thread, 9.525mm long.
- 9 Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine thread.
- 10 Socket base nut: 18-8 Stainless steel, 0-80 fine thread.
- 11 Nylon washer: 1.73mm ID; 4.78mm OD 0.64mm thickness.

### SG-BGA-6215 Drawing

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11351 Rupp Dr. Ste 400 Burnsville, MN 55337  
(952)229-8200  
www.ironwoodelectronics.com

Status: Released

Scale: -

Rev: B

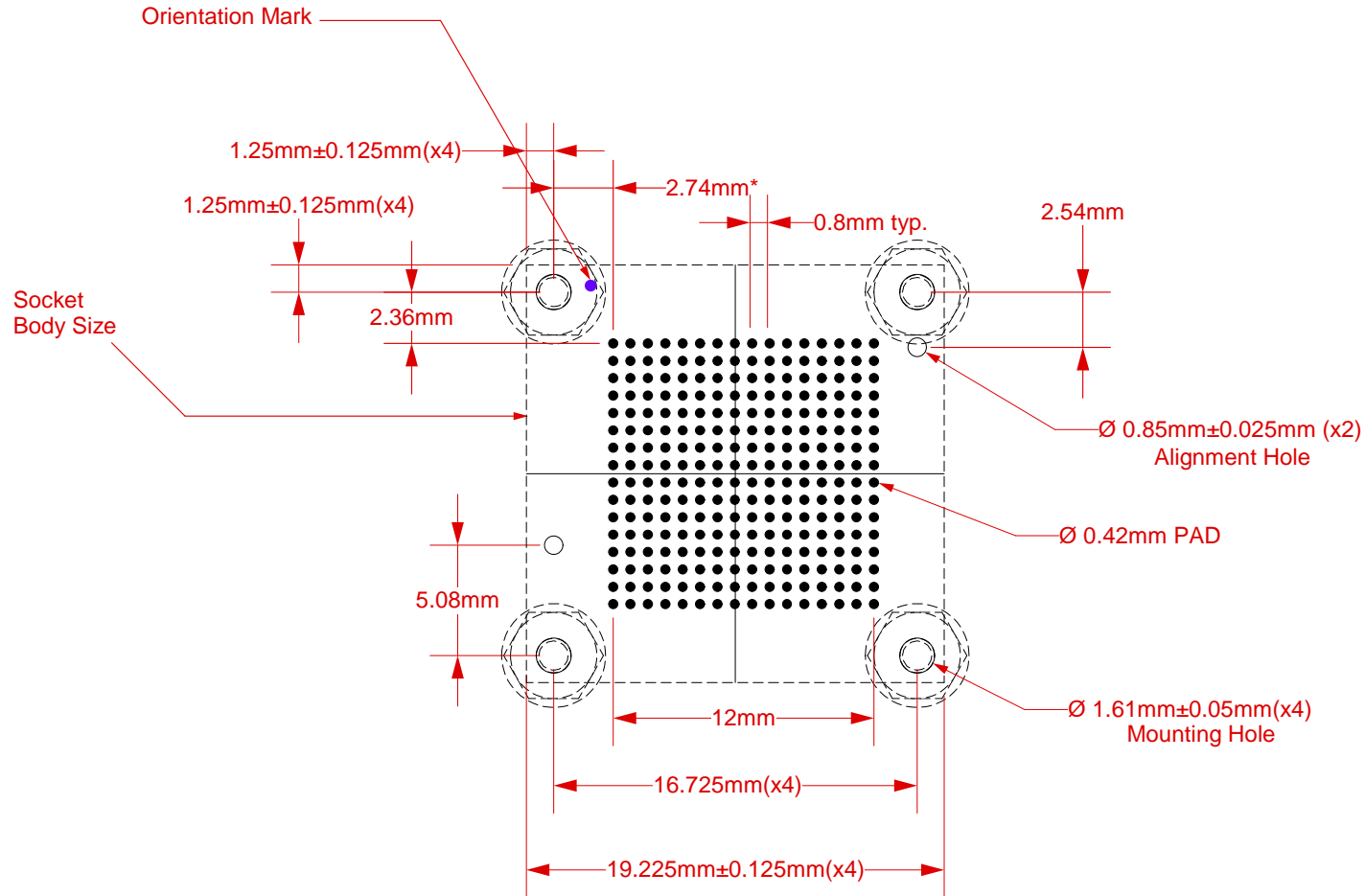
Drawing: J. Glab

Date: 12/14/06

File: SG-BGA-6215 Dwg.mcd

Modified: 6/2/09, AE

All tolerances:  $\pm 0.125$ mm (unless stated otherwise). Materials and specifications are subject to change without notice.




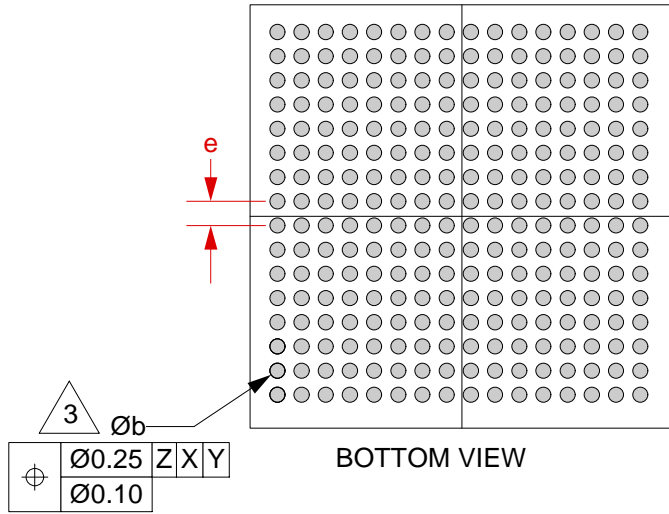
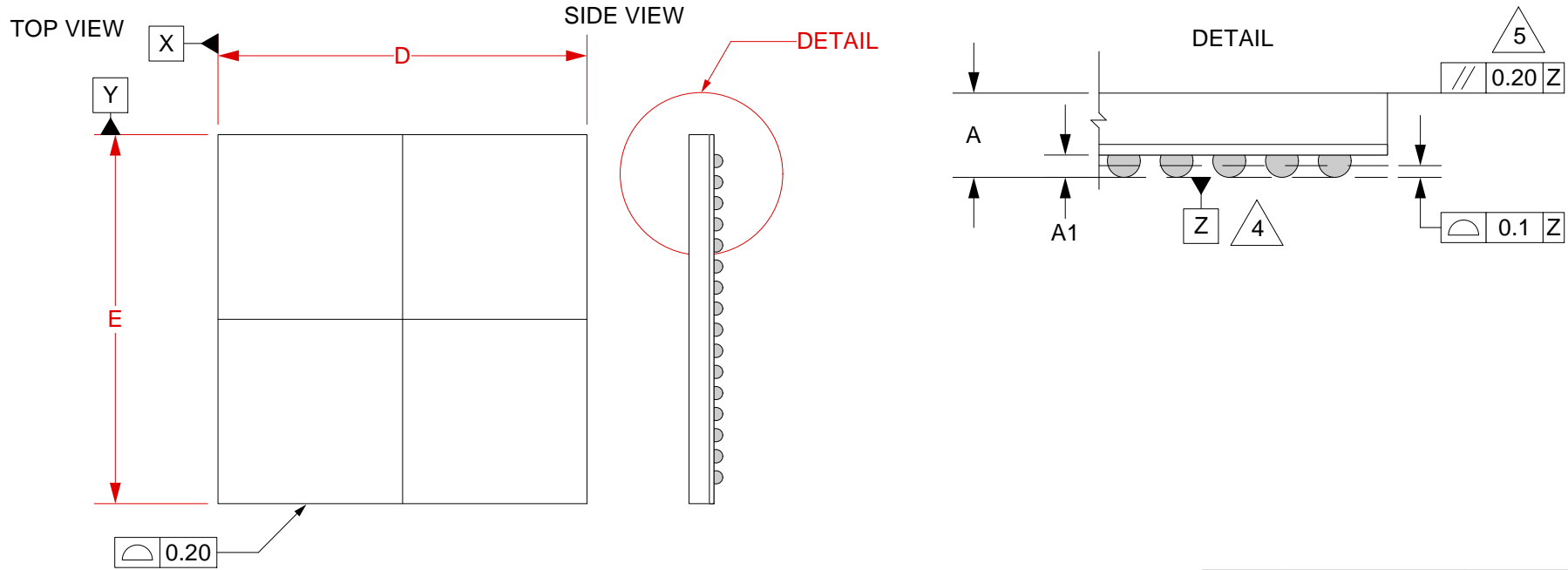
**Target PCB Recommendations**

Total thickness: 1.6mm min.  
Plating: Gold or Solder finish  
PCB Pad height: Same or higher than solder mask

NOTE: Steel backing plate may be required based on end user's application

Recommended PCB Layout Tolerances: ±0.025mm [±0.001"] unless stated otherwise.


	<b>SG-BGA-6215 Drawing</b>	Status: Released	Scale: 3:1	Rev: B
	© 2005 IRONWOOD ELECTRONICS, INC. 11351 Rupp Dr. Ste 400 Burnsville, MN 55337 (952)229-8200 www.ironwoodelectronics.com	Drawing: J. Glab	Date: 12/14/06	
		File: SG-BGA-6215 Dwg.mcd	Modified: 6/2/09, AE	



- 1 Dimensions are in millimeters.
- 2 Interpret dimensions and tolerances per ASME Y14.5M-1994.
- 3 Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
- 4 Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
- 5 Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		2.20
A1	0.2	0.34
b	0.40	0.60
D	14.00 BSC	
E	14.00 BSC	
e	0.80 BSC	

Array 16x16

	<b>SG-BGA-6215 Drawing</b>		Status: Released	Scale: -	Rev: B	
	© 2005 IRONWOOD ELECTRONICS, INC. 11351 Rupp Dr. Ste 400 Burnsville, MN 55337 (952)229-8200 www.ironwoodelectronics.com			Drawing: J. Glab		Date: 12/14/06
				File: SG-BGA-6215 Dwg.mcd		Modified: 6/2/09, AE